



Features

Technique

Glass Passivated Die Construction Ideal for Printed Circuit Board

10A STANDARD RECOVERY BRIDGE RECTIFIER

For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please

Reliable Low Cost Construction Utilizing Molded Plastic

Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
Halogen and Antimony Free. "Green" Device (Note 3)

contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Product Summary

| VRRM (V) | I _F (A) | V _F Max (V) @ I _F = 5A | I _R Max (μA) | |
|----------|--------------------|---|-------------------------|--|
| 1000 | 10 | 1.05 | 5 | |

Mechanical Data

- Package: TTL
- Package Material: "Green" Molding Compound, UL Flammability Classification 94V-0 (No Br. Sb. Cl.)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Polarity Indicator: As Marked on the Body
- Weight: 0.41 grams (Approximate)

TTL





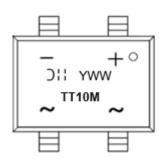
Ordering Information (Note 4)

| Part Number | Pankaga | Packing | | |
|-------------|---------|---------|---------|--|
| Part Number | Package | Qty. | Carrier | |
| TT10M-13 | TTL | 1500 | Reel | |

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



TT10M = Product Type Marking Code

O!! = Manufacturer's Code Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 2 = 2022)

WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|--|---|--------------------|-------------|------------------|
| Maximum Repetitive Peak Reverse Voltage | | V_{RRM} | 1000 | V |
| Maximum DC Blocking Voltage | | V_{DC} | 1000 | V |
| Average Rectified Output Current | @T _A = +25°C (Note 5) | I _{F(AV)} | 10 | Α |
| Peak Forward Surge Current 8.3ms Single Half Sine-Wave | @T _A = +25°C @T _A = +125°C | IFSM | 180 144 | А |
| Peak Forward Surge Current 1.0ms Single Half Sine-Wave | @T _A = +25°C @T _A = +125°C | IFSM | 360 288 | А |
| I ² t Rating for Fusing (t = 8.3ms) | | l ² t | 135 | A ² s |
| Operating and Storage Temperature Range | | TJ, TSTG | -55 to +150 | °C |

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Test Condition | | Symbol | Тур. | Max | Unit |
|---------------------------------------|------------------------|-------------------------|--------|------|------|------|
| Forward Voltage (Note 5) | IF = 5A | T _A = +25°C | VF | 0.98 | 1.05 | V |
| | | T _A = +125°C | | 0.88 | _ | |
| Leakage Current | V _R = 1000V | T _A = +25°C | IR | 0.2 | 5 | μΑ |
| | | T _A = +125°C | | 70 | 500 | |
| Typical Junction Capacitance (Note 6) | | Ст | 5 | 0 | pF | |

Thermal Characteristics

| Characteristic | Symbol | Тур. | Unit |
|---|----------------------|----------------|------|
| Typical Thermal Resistance (Without Heatsink) | Røjc Røjl Røja | 11 13 72 | °C/W |
| Typical Thermal Resistance (Note 7) | Rejc Rejl Reja | 2 5 10 | °C/W |

Notes:

- 5. Perform static test after the temperature of oven is steady for 20 minutes.
- 6. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.7. Thermal resistance junction to case, lead and ambient in accordance with JESD-51.



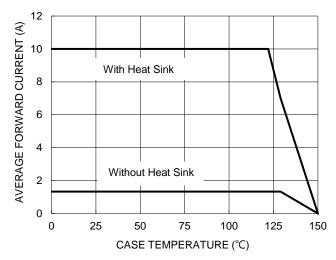
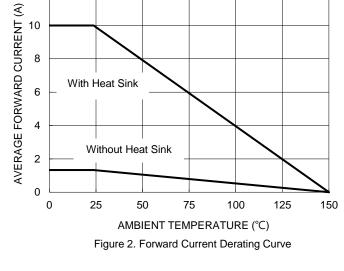


Figure 1. Forward Current Derating Curve



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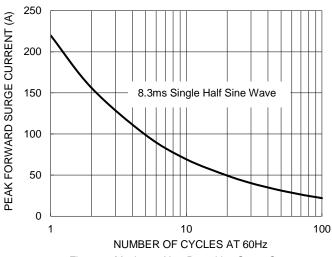


Figure 3. Maximum Non-Repetitive Surge Current

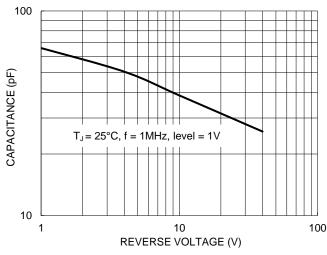


Figure 4. Typical Junction Capacitance

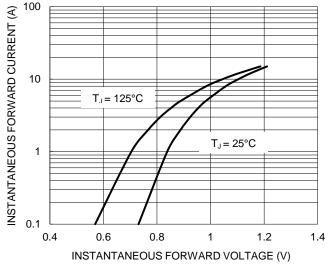


Figure 5. Typical Forword Characteristics

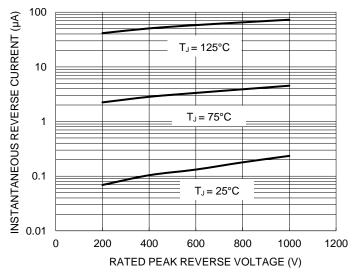
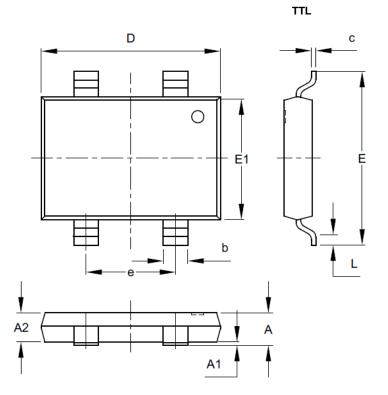


Figure 6. Typical Reverse Characteristics



Package Outline Dimensions

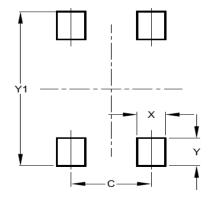
Please see http://www.diodes.com/package-outlines.html for the latest version.



| ΠL | | | | |
|----------------------|-------|-------|-------|--|
| Dim | Min | Max | TYP | |
| Α | 1.45 | 1.80 | 1.65 | |
| A1 | 0.00 | 0.15 | 0.10 | |
| A2 | 1.45 | 1.65 | 1.55 | |
| b | 1.30 | 1.50 | 1.40 | |
| С | 0.15 | 0.35 | 0.25 | |
| D | 10.05 | 10.35 | 10.20 | |
| Е | 9.75 | 10.05 | 9.90 | |
| E1 | 6.85 | 7.15 | 7.00 | |
| Е | 4.90 | 5.10 | 5.00 | |
| L | 0.45 | 0.95 | 0.70 | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

TTL



| Dimensions | Value (in mm) | |
|------------|------------------|--|
| С | 5.00 | |
| Х | 1.80 | |
| Y | 2.10 | |
| Y1 | 11.70 | |